IPC ASSOCIATION ELECTRONIE	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
Supplie	r Information						·								
Company	name*	Company unique ID			J	Unique ID Authority					Response Date*				
nsemi											2023-06-08				
Contact N	Name	Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	te Version Manufacturing Site		ring Site	V	Veight*	UOM	Unit Type	
		FDMF5821DC Smart Power Sta		Smart Power Stage	e Module		2023-06-08		I	PBB		8	5.215	mg	Each
Ianufa	ecturing Process Inform														
	3		-		-STD-020 MSL	Rating		ess Body	ss Body Temperature   Max Time at Peak		me at Peak	•		per of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30		second	ls  3		
omments															
	naximum time at peak tempera														
or more	information regarding materi	al composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not independently verified information provided by others, supplier as a minimum, its applier by the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's St											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip (Heat sink)	26.983	mg	Supplier	Zinc (Zn)	7440-66-6		0.035	mg
			Supplier	Iron (Fe)	7439-89-6		0.648	mg
			Supplier	Copper (Cu)	7440-50-8		26.3	mg
Die	1.31	mg	Supplier	Silicon (Si)	7440-21-3		1.31	mg
Die Attach Solder	3.524	mg	Supplier	Silver (Ag)	7440-22-4		0.0881	mg
			A	Lead (Pb)	7439-92-1	7a	3.2597	mg
			Supplier	Tin (Sn)	7440-31-5		0.1762	mg
Lead Frame	27.291	mg	Supplier	Silver (Ag)	7440-22-4		0.3	mg
			Supplier	Zinc (Zn)	7440-66-6		0.036	mg
			Supplier	Iron (Fe)	7439-89-6		0.655	mg
			Supplier	Copper (Cu)	7440-50-8		26.3	mg
Mold Compound-Black	23.412	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		2.11	mg
			Supplier	Carbon Black (C)	1333-86-4		0.234	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.6	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.468	mg
Plating	1.73	mg	Supplier	Tin (Sn)	7440-31-5		1.73	mg
Wire Bond - Au	0.088	mg	Supplier	Gold (Au)	7440-57-5		0.088	mg
Wire Bond - Cu	0.877	mg	Supplier	Palladium (Pd)	7440-05-3		0.0175	mg
			Supplier	Copper (Cu)	7440-50-8		0.8595	mg